

PATENTS ONLY (ref OG 7/28/92)

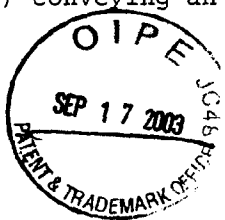
09-24-2003



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To the Honorable Commissioner  
Please record the attached original document or copy thereof.

1. Name of Party(ies) conveying an interest:  
Toru ISHIDA  
Tetsuharu URAWA  
Fujio ITO  
Tomoo MATSUZAWA  
Kazunari SUZUKI  
Akihiko KAMEOKA  
Hiromichi SUZUKI  
Takuji IDE
2. Name and Address of Party(ies) receiving an interest:  
HITACHI, LTD.  
6, Kanda Surugadai 4-chome  
Chiyoda-ku, Tokyo, JAPAN  
  
HITACHI ULSI SYSTEMS, CO., LTD.  
22-1, Josuihoncho 5-chome  
Kodaira-shi, Tokyo, Japan  
  
HITACHI HOKKAI SEMICONDUCTOR, LTD.  
145, Azanakajima, Nanaecho,  
Kameda-gun, Hokkaido, Japan

3. Description of the interest conveyed: Assignment

4. Application number(s) or patent number(s).

Additional sheet attached? Yes XXX NoIf this document is being filed together with a new application,  
the execution date of the application is: \_\_\_\_\_

DATE

A. Patent Application No.(s)

B. Patent No.(s)

09/964,484

5. Name and address of party to whom correspondence concerning document should be mailed:

John R. Mattingly  
Mattingly, Stanger & Malur, P.C.  
1800 Diagonal Road, Suite 370  
Alexandria, Virginia 22314

6. Number of applications and patents involved: One7. Amount of fee enclosed or authorized to be charged: \$40.00

8. The Commissioner is hereby authorized to charge Deposit Account No. 50-1417 if no check is attached.

09/18/2003 BABRAHA1 00000043 09964484

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9. Execution date of attached document: September 1, 3, 4 and 5, 2001

10. To the best of my knowledge and belief, I declare under penalty of perjury under the laws of the United States of America that the foregoing information is true and correct and that any attached copy is a true copy of the original document.

John R. Mattingly  
Name of Person Signing

Signature

September 17, 2003  
Date

Total number of pages being submitted: 2

# ASSIGNMENT

( 譲 渡 証 )

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI, LTD., Hitachi ULSI Systems Co., Ltd. and Hitachi Hokkai Semiconductor, Ltd., corporations organized under the laws of Japan, located at 6, Kanda Surugadai 4-chome, Chiyoda-ku, Tokyo, Japan ; 22-1, Josuihoncho 5-chome, Kodaira-shi, Tokyo, Japan and 145, Azanakajima, Nanaecho, Kameda-gun, Hokkaido, Japan, respectively, receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI, LTD., Hitachi ULSI Systems Co., Ltd. and Hitachi Hokkai Semiconductor, Ltd., their successors and assigns, all my right, title and interest, in and for the United States of America, in and to

## A SEMICONDUCTOR DEVICE

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire owner ship of the said Letters Patent when granted, to be held and enjoyed by said HITACHI, LTD., Hitachi ULSI Systems Co., Ltd. and Hitachi Hokkai Semiconductor, Ltd., their successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI, LTD., Hitachi ULSI Systems Co., Ltd. and Hitachi Hokkai Semiconductor, Ltd.

Signed on the date(s) indicated aside signatures:

INVENTOR(S) (発明者フルネームサイン)		Date Signed (署名日)
1) <u>Toru Ishida</u> (Toru ISHIDA)	<u>Sept. 11 / 2001</u>	
2) <u>Tetsuharu Urawa</u> (Tetsuharu URAWA)	<u>1 / September / 2001</u>	
3) <u>Fujio Ito</u> (Fujio ITO)	<u>4 / September / 2001</u>	
4) <u>Tomoo Matsuzawa</u> (Tomoo MATSUZAWA)	<u>5 / September / 2001</u>	
5) <u>Kazunari Suzuki</u> (Kazunari SUZUKI)	<u>5 / September / 2001</u>	
6) <u>Akihiko Kameoka</u> (Akihiko KAMEOKA)	<u>3 / September / 2001</u>	
7) <u>Hiromichi Suzuki</u> (Hiromichi SUZUKI)	<u>4 / September / 2001</u>	
8) <u>Takuji Ide</u> (Takuji IDE)	<u>5 / September / 2001</u>	
9) _____	_____	
10) _____	_____	